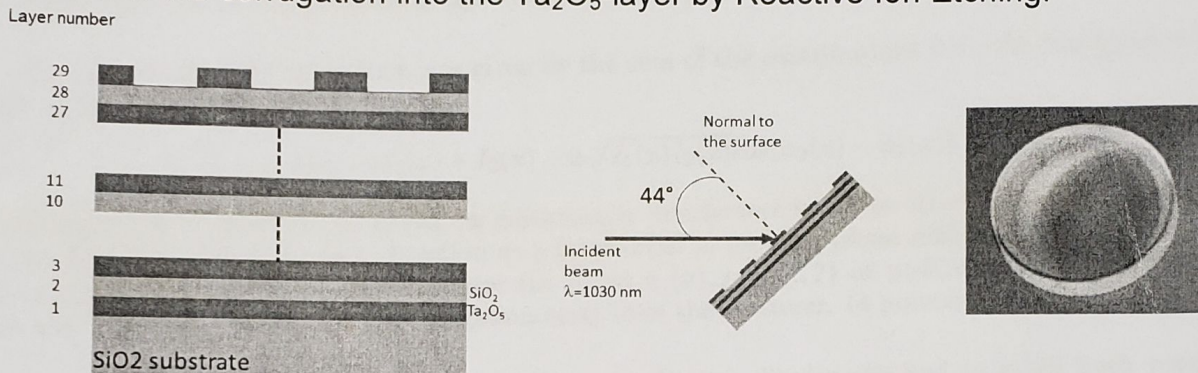


Examination Micro- and Nano-Technology

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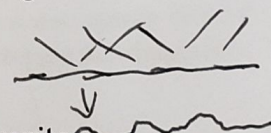
Diffraction gratings are optical components which have various applications. Here we will study a specific case: the fabrication of a multilayer grating for ultra-short pulse compression.

The grating to be fabricated should be made on a 25 mm diameter SiO_2 substrate on a multi-layer stack (29 layers of alternating Ta_2O_5 [$h=126\text{nm}$, $n=2.15$] and SiO_2 [$h=192\text{nm}$, $n=1.51$]), the corrugation is in the final Ta_2O_5 -layer on top of the last SiO_2 layer [see figure]. The method used to write the grating is: transfers the periodic pattern into a $1\mu\text{m}$ thick positive photoresist layer by two beam interference lithography (by means of a He-Cd laser emitting at the wavelength of $\lambda=442\text{nm}$) and then transfer the corrugation into the Ta_2O_5 -layer by Reactive Ion Etching.



Left: Schematic sketch of the multilayer grating. Middle: Operation mode of the final component. Right: Picture of the final component. (Ref.: Rumpel et al. "Broadband pulse compression gratings with measured 99.7% diffraction efficiency," Opt. Lett. 39 (2014)).

Questions:

- 1) The grating has a line density of 1250 lines/mm, what is its period in nm? $P = 1250^{-1}$
- 2) At a wavelength of 1030nm, and an incidence angle of 44° , what is the angle of diffraction of the -1^{st} order in reflection in air? $\sin \alpha + \sin \beta = \frac{m\lambda}{P}$
- 3) Describe in few sentences and a sketch the principle of the two-beam interference lithography. 
- 4) According to the wavelength of the laser and the period of the grating to write, what is the value of the angle between the beams for the lithographic step?
- 5) Starting from a SiO_2 substrate, make a flow chart describing all the steps to fabricate the final component (coating, lithography, development, and etching). Describe only the coating of the 2 first layers and of the last 2 of the stack.
- 6) Cite some coating techniques for the deposition of Ta_2O_5 and SiO_2 (coating of dielectric materials in general). PVD CVD oxidation
- 7) Which technique should be used for the coating of the photoresist? Justify your choice with a few words!
- 8) The duty cycle of the grating is 25%, what is the width in nm of the Ta_2O_5 lines? How can the duty cycle be controlled during the two-beam interference lithography step (which parameters can be adjusted)?
- 9) Which characterization techniques can be used to measure the profile (thickness and duty cycle) of the fabricated grating? Justify your choice with a few words.
- 10) Assume that a series of 100 gratings has to be fabricated. Explain with a few sentences an alternative lithographic method to produce the resist mask of the grating!
- 11) Bonus: What is the purpose of the multi-layer stack under the grating? $\text{multiple reflection}$